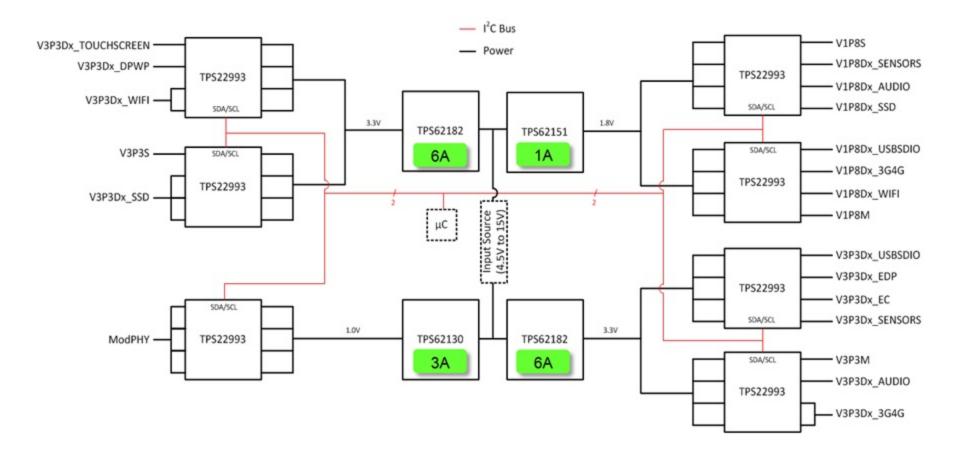
TIDA-00194 Skylake Block Diagram





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